

Accelerating Artificial
Intelligence and Leading
Efficiency

## GS3 | G593-SD1-AAX3

Let Hyperscalers meet your bespoke requirements!

Start customizing your GS3 | G593-SD1-AAX3 today!

- NVIDIA HGX™ H200 8-GPU
- 900GB/s GPU-to-GPU bandwidth with NVIDIA® NVLink™ and NVSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA BlueField®-3
  DPUs/SuperNICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x FHHL PCIe Gen5 x16 slots
- 8 x LP PCIe Gen5 x16 slots
- 4+2 3000W 80 PLUS Titanium redundant power supplies

### About Hyperscalers



World's First Open OEM



Free Of Proprietary Software Lock-Ins



Free Of Proprietary Hardware Lock-Ins



US Stock



Full US Warranty



100% Channel Distributor

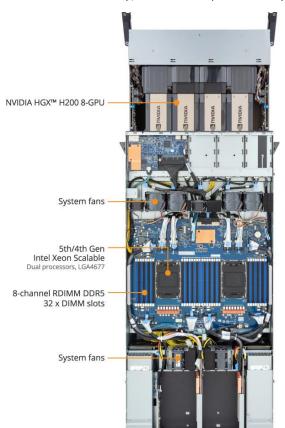


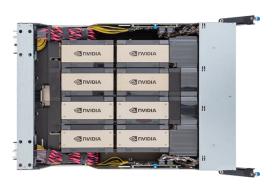
Metro Delivery 1-4 Days



# HPC/AI Server - 5th/4th Gen Intel® Xeon® Scalable - 5U DP NVIDIA HGX™ H200 8-GPU

The NVIDIA HGX<sup>™</sup> H200 combines H200 Tensor Core GPUs with high-speed interconnects to deliver extraordinary performance, scalability, and security for every data center. Configurations of up to eight GPUs deliver unprecedented acceleration, with a staggering 32 petaFLOPS of performance to create the world's most powerful accelerated scale-up server platform for AI and HPC. An eight-way HGX H200 provides over 32 petaflops of FP8 deep learning compute and 1.1TB of aggregate high-bandwidth memory. NVIDIA HGX<sup>™</sup> H200 also includes NVIDIA BlueField®-3 data processing units (DPUs) to enable cloud networking, composable storage, zero-trust security, and GPU compute elasticity in hyperscale AI clouds.



















# GS3 | G593-SD1-AAX3 Specifications

Processor  Form Factor	CPU: 5th Gen Intel® Xeon® Scalable Processors 4th Gen Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Motherboard: MSB3-G41 Max. TDP Support: 350W Number of Processors: 2 Processors		Modular GPU: NVIDIA HGX™ H200 with 8 x SXM GPUs
		Backplane	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
		Cumply	4+2 x 3000W 80 PLUS Titanium redundant power supplies
		,	AC Input: - 115-127V~/ 14.2A, 50-60Hz
Dimensions	<b>W x H x D (mm):</b> 447 × 219.7 × 945		
Socket	2 x LGA 4677 Socket E		- 200-220V~/ 15.8A, 50-60Hz
Chipset	Intel® C741 Series	  -  -  -  -	- 220-240V~/ 14.9A, 50-60Hz DC Input: (Only for China) - 240Vdc/ 14A DC Output: - Max 1450W/ 115-127V~ +54V/ 26.6A, +12Vsb/ 3A - Max 2900W/ 200-220V~ +54V/ 53.4A,
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA (NVMe from PEX89104) Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x2, from PCH 1 x M.2 (2280/22110), PCIe Gen3 x1, from PCH SAS: Require SAS add-in cards RAID: Intel® SATA RAID 0/1/10/5 (Support optional RAID add-in cards)		
Memory	Total Slots: 32 x DIMM slots  Memory Type: DDR5 memory supported (8-Channel memory per processor)  Speed: 5th Gen Xeon: RDIMM: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC) 4th Gen Xeon: RDIMM: Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC) Xeon Max Series: RDIMM: Up to 4800 MT/s (1DPC), 4400 MT/s (2DPC)		+12Vsb/ 3A - Max 3002.4W/ 220-240V~ or 240V dc Input +54V/ 55.6A, +12Vsb/ 3A
		Onboard Storage	(2) 2280 PCIe M.2 for Booting OS
		Fan	Motherboard: 2 x 40x40x28mm (25,000rpm)
Expansion Slot	Extension Board CPBG044 x 2: - 8 x LP x16 (Gen5 x16), from PEX89104 Riser Card CPBGD20 x 2: - 4 x FHHL x16 (Gen5 x16), from PEX89048		4 x 60x60x56mm (24,000rpm)  PCIe slots:  4 x 40x40x28mm (25,000rpm)  2 x 40x40x56mm (32,000rpm)  GPU tray:  6 x 60x60x76mm (21,700rpm)  11 x 80x80x80mm (17,000rpm)
Front I/O	I/O board - CDCG120: 2 x USB 3.2 Gen1 ports (Type-A) 1 x VGA port		
	2 x RJ45 ports 1 x MLAN port (default) 1 x Power button with LED 1 x ID button with LED	Video	Integrated in ASPEED® AST2600 - 1 x VGA port
		System Management	ASPEED® AST2600 Baseboard  Management Controller
	1 x NMI button 1 x Reset button	Rear I/O	MLAN board - CDB66: 1 x MLAN port
	1 x Reset button 1 x Storage activity LED 1 x System status LED	Operating Environment	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-
LAN	Front (I/O board - CDCG120):  2 x 10Gb/s LAN (1 x Intel® X710-AT2) - Support NCSI function  1 x 10/100/1000 Mbps Management LAN  Rear (MLAN board - CDB66):		condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non- condensing)
Authori Hyperso	5%2	ТРМ	Security Modules: 1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010

### **About Hyperscalers**

Partner

Hyperscalers is the world's first open Original Equipment Manufacturer offering proprietary-free alterative to traditional Tier 1  ${\sf OEM}$  vendors.

Hereto to solve Information technology's complexity, Hyperscalers developed the IP Appliance Design Process. Which is basically a process along with a utility, being the Appliance Optimizer Utility, which together, assists service providers 'productize' delivery of their Digital-IP.

#### **Technology Partners**



Micron

Western Digital











#### **Hyperscalers** Australia Head Quaters

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